



Final Product Change Notification

201404006F01

Issue Date: 14-Sep-2015
Effective Date: 28-Dec-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | |
|----------------------------------------------|---------------------------------------------|---------------------------------------------------------|----------------------------------------------------|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Qualification of D4 R0-clip overhang removal for a subset of LFPAK devices

Details of this Change

The shape of the source clip on a subset of LFPAK device types is to be optimised. It will be reduced in overall dimension to make it smaller in size than the die size.

As part of this change NXP are also taking this opportunity to update the die design of BUK9Y40-55B to bring in line with all the other types to align with best practice. All types, with the exception of BUK9Y40-55B, currently utilise rounded corners in the Trench network which results in the product to be more robust to voltage overstress.

Why do we Implement this Change

Recent reliability studies on LFPAK device types have highlighted a low line PPM risk with the current clip. The optimised source clip is to be made to eliminate the failure mode, in line with NXP's Zero Defects policy.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 28-Dec-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
--------------	------------	----------------	-------

201404006A	14-Apr-2014		Qualification of D4 R0-clip overhang removal for a subset of LFPAK devices
------------	-------------	--	----------------------------------------------------------------------------

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 14-Oct-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address powermos.pcn@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.